



**TRANSISTORS, POWER, MOSFET, N-CHANNEL,  
RAD-HARD**

**BASED ON TYPES BUY25CS12K-01,  
BUY25CS12K-11 AND BUY25CS45B-01**

**ESCC Detail Specification No. 5205/030**

Issue 2	September 2019
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**1 GENERAL**

**1.1 SCOPE**

This specification details the ratings, physical and electrical characteristics and test and inspection data for the component type variants and/or the range of components specified below. It supplements the requirements of, and shall be read in conjunction with, the ESCC Generic Specification listed under Applicable Documents.

**1.2 APPLICABLE DOCUMENTS**

The following documents form part of this specification and shall be read in conjunction with it:

- (a) ESCC Generic Specification No. [5000](#)
- (b) [MIL-STD-750](#), Test Methods and Procedures for Semiconductor Devices

**1.3 TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS**

For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESCC Basic Specification No. [21300](#) shall apply.

**1.4 THE ESCC COMPONENT NUMBER AND COMPONENT TYPE VARIANTS**

**1.4.1 The ESCC Component Number**

The ESCC Component Number shall be constituted as follows:

Example: 520503001R

- Detail Specification Reference: 5205030
- Component Type Variant Number: 01 (as required)
- Total Dose Radiation Level Letter: R (as required)

**1.4.2 Component Type Variants**

The component type variants applicable to this specification are as follows:

Variant Number	Based on Type	$I_{DS}$ @ $T_{case} \leq +25^{\circ}C$ max A (Note 1)	$I_{DS}$ @ $T_{case} = +100^{\circ}C$ max A (Note 1)	$r_{DS(on)}$ @ $T_{amb} = +25^{\circ}C$ max m $\Omega$ (Note 2)	Case (Note 3)	Pin Out (Note 3)	Weight max g	Total Dose Radiation Level Letter
01	BUY25CS12K-01	12.4	8	130	TO-257AA	1: Drain 2: Source 3: Gate	5.1	R [100kRAD(Si)]
02	BUY25CS12K-11	12.4	8	130	TO-257AA	1: Gate 2: Drain 3: Source	5.1	R [100kRAD(Si)]
03	BUY25CS45B-01	45	29	50	TO-254AA	1: Drain 2: Source 3: Gate	9.5	R [100kRAD(Si)]

**NOTES:**

1. See Para. 1.5.
2. See Para. 2.5.1.
3. See Para. 1.7.
4. Total dose radiation level letters are defined in ESCC Basic Specification No. [22900](#). If an alternative radiation test level is specified in the Purchase Order the letter shall be changed accordingly.

1.5 MAXIMUM RATINGS

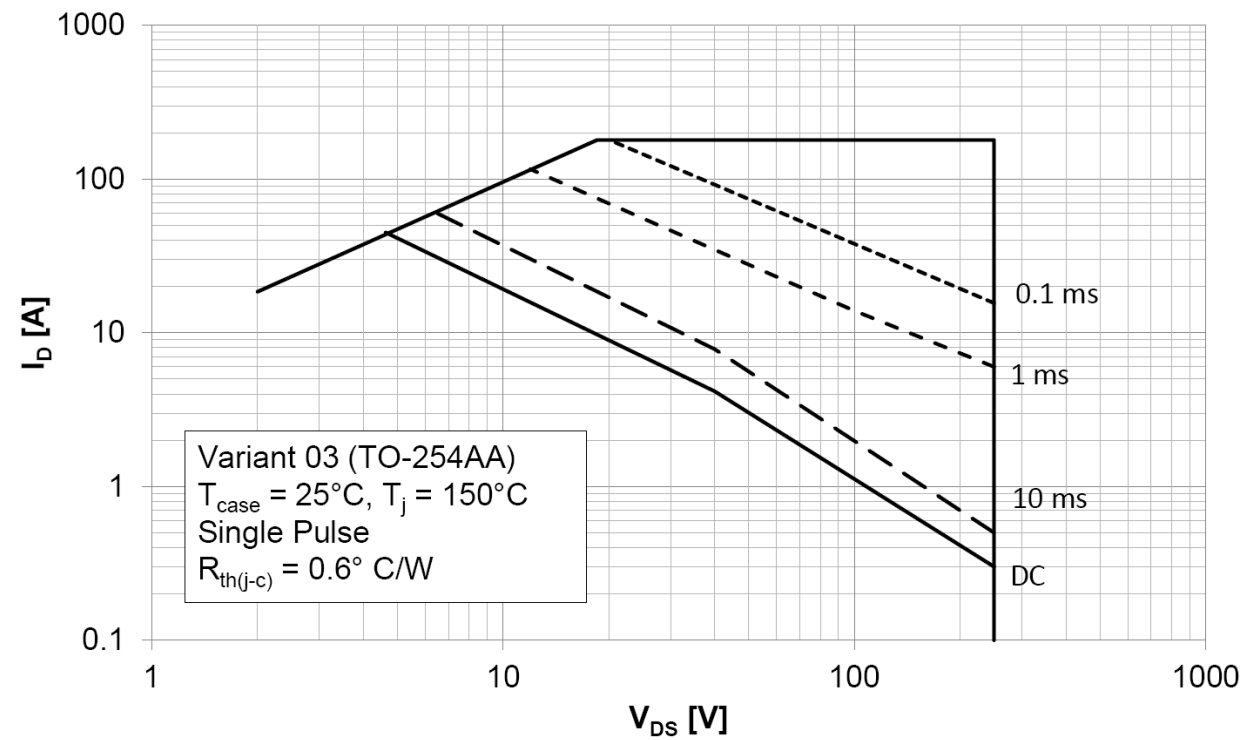
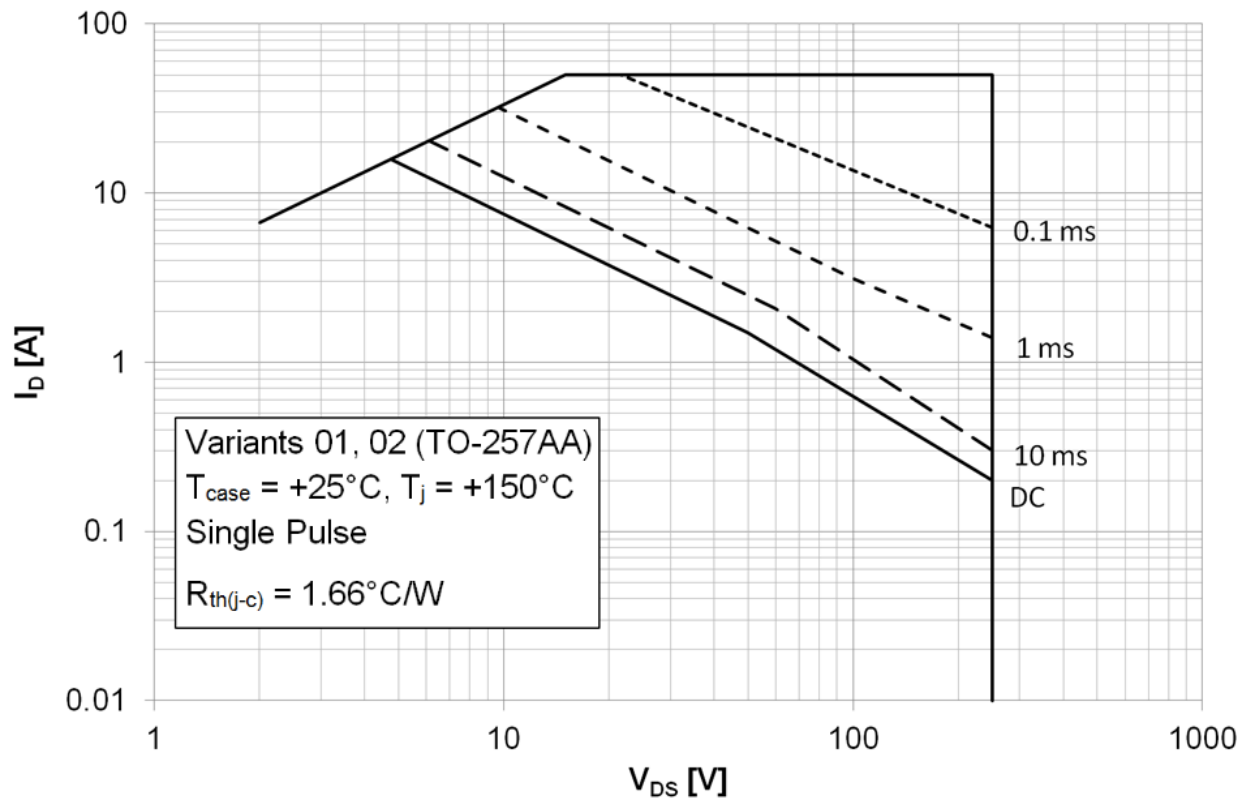
The maximum ratings shall not be exceeded at any time during use or storage.

Maximum ratings shall only be exceeded during testing to the extent specified in this specification and when stipulated in Test Methods and Procedures of the ESCC Generic Specification.

Characteristics	Symbols	Maximum Ratings	Units	Remarks
Drain-Source Voltage	$V_{DS}$	250	V	Note 1
Gate-Source Voltage	$V_{GS}$	20	V	
Drain Current (Continuous)	$I_{DS}$	Note 2	A	At $T_{case} \leq +25^{\circ}C$ Notes 1, 3, 4
		Note 2	A	At $T_{case} = +100^{\circ}C$ Notes 3, 4
Drain Current (Pulsed) Variants 01, 02: Variant 03:	$I_{DM}$	50 180	Apk	At $T_{case} \leq +25^{\circ}C$ Notes 1, 3
Power Dissipation Variants 01, 02: Variant 03:	$P_{tot}$	75 208	W	Note 5
Avalanche Energy (Single Pulse) Variants 01, 02: Variant 03:	$E_{AS}$	60 380	mJ	
Operating Temperature Range	$T_{op}$	-55 to +150	$^{\circ}C$	$T_{amb}$
Storage Temperature Range	$T_{stg}$	-55 to +150	$^{\circ}C$	
Junction Temperature	$T_j$	+150	$^{\circ}C$	
Soldering Temperature	$T_{sol}$	+250	$^{\circ}C$	Note 6
Thermal Resistance, Junction-to-Case Variants 01, 02: Variant 03:	$R_{th(j-c)}$	1.66 0.6	$^{\circ}C/W$	

**NOTES:**

1. Safe Operating Area applies as follows:



2. See Para. 1.4.2 for  $I_{DS}$  value.
3.  $T_{case}$  is measured on the PCB at the soldering point to the Drain terminal.
4. For  $T_{case} > +25^{\circ}C$ , derate as follows:

$$I_{DS} = \sqrt{\frac{T_{jmax} - T_{case}}{(R_{th(j-c)}) \times (r_{DS(on)} \text{ at } T_{jmax})}}$$

where ( $r_{DS(on)}$  at  $T_{jmax}$ ) =

- For Variant 01: 490m $\Omega$
  - For Variant 02: 490m $\Omega$
  - For Variant 03: 103m $\Omega$
5. For  $T_{case} > +25^{\circ}C$ , derate linearly to 0W at  $T_{case} = +150^{\circ}C$ .
  6. Duration 10 seconds maximum and the same terminal shall not be resoldered until 3 minutes have elapsed.

## 1.6 HANDLING PRECAUTIONS

The TO-257AA and TO-254AA packages contain Beryllium Oxide (BeO) and therefore must not be ground, machined, sandblasted or subjected to any mechanical operation which will produce dust. The case must not be subjected to any chemical process (e.g. etching) which will produce fumes.

These devices shall not be handled by the terminals.

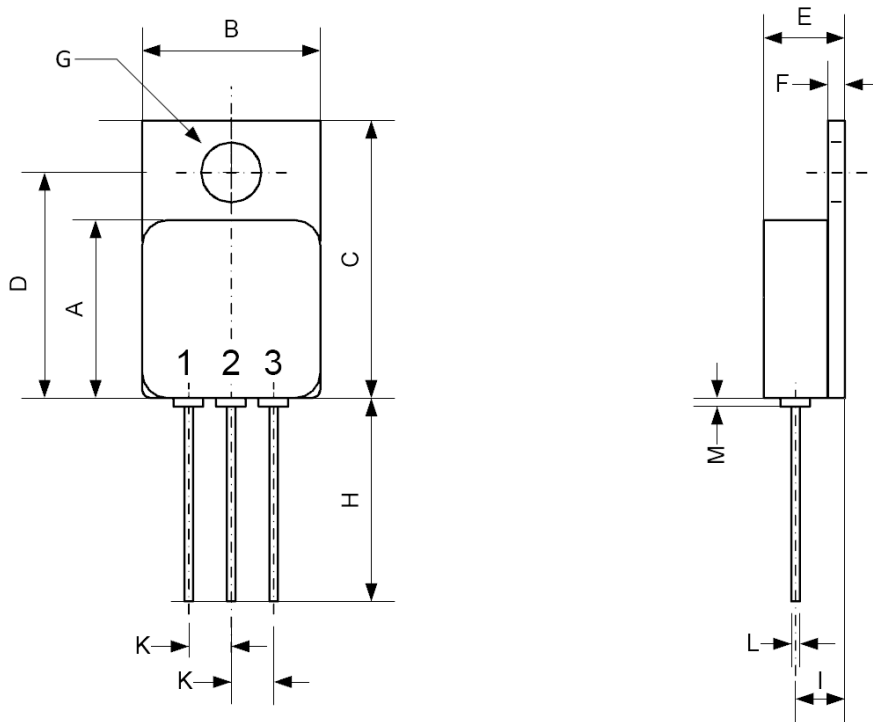
These devices are susceptible to damage by electrostatic discharge. Therefore, suitable precautions shall be employed for protection during all phases of manufacture, testing, packaging, shipment and any handling.

These components are categorised as Class 1 per ESCC Basic Specification No. [23800](#) with a Minimum Critical Path Failure Voltage of 1000V.



1.7 PHYSICAL DIMENSIONS AND TERMINAL IDENTIFICATION

1.7.1 TO-257AA and TO-254AA Packages – 3 Terminals



Symbols	Dimensions mm			
	Variants 01, 02 (TO-257AA)		Variant 03 (TO-254AA)	
	Min	Max	Min	Max
A	10.4	10.8	13.5	13.9
B	10.4	10.8	13.5	13.9
C	16.2	16.8	19.9	20.4
D	13.1	13.9	16.8	17.5
E	4.8	5.4	6.4	6.9
F	0.9	1.1	1	1.3
G	3.5	3.7	3.5	3.8
H	14	19	12.9	15
I	2.7	3.2	3.6	4
K	2.54 BSC	2.54 BSC	3.81 BSC	3.81 BSC
L	0.6	1	0.8	1.2
M	-	1.3	-	1.3

**NOTES:**

- The terminal identification is specified by the component's geometry. The terminal identification shall be as follows:
  - Variants 01, 03: terminal 1 = Drain; terminal 2 = Source; terminal 3 = Gate
  - Variant 02: terminal 1 = Gate; terminal 2 = Drain; terminal 3 = Source

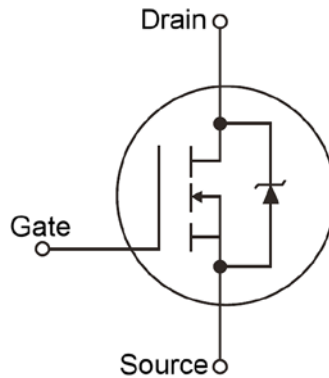
## 1.8 FUNCTIONAL DIAGRAM

### Variants 01, 03:

Terminal 1: Drain  
Terminal 2: Source  
Terminal 3: Gate

### Variant 02:

Terminal 1: Gate  
Terminal 2: Drain  
Terminal 3: Source



### **NOTES:**

1. The case is not connected to any terminal.

## 1.9 MATERIALS AND FINISHES

Materials and finishes shall be as follows:

- (a) Case  
The case shall be hermetically sealed and have a ceramic/metal body.
- (b) Terminals  
The terminal material and finish shall be either D14 or H14 in accordance with the requirements of ESCC Basic Specification No. [23500](#).

## 2 REQUIREMENTS

### 2.1 GENERAL

The complete requirements for procurement of the components specified herein are as stated in this specification and the ESCC Generic Specification. Permitted deviations from the Generic Specification, applicable to this specification only, are listed below.

Permitted deviations from the Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalent to the ESCC requirement and do not affect the component's reliability, are listed in the appendices attached to this specification.

#### 2.1.1 Deviations from the Generic Specification

##### 2.1.1.1 *Deviations from Screening Tests - Chart F3*

- (a) Verification of Safe Operating Area: The Safe Operating Area shall be verified by performing the Thermal Impedance ( $Z_{th(j-s)}$ )  $\Delta V_{SD}$  test specified in Para. 2.5.1 Room Temperature Electrical Measurements.
- (b) Particle Impact Noise Detection may be performed at any point after Temperature Cycling, prior to Seal.
- (c) Power Burn-in: A high temperature steady-state gate bias test (HTGB) (see Para. 2.9) shall be performed instead of Power Burn-in.
- (d) Radiographic Inspection: Not applicable.

**2.2 MARKING**

The marking shall be in accordance with the requirements of ESCC Basic Specification No. 21700 and as follows.

The information to be marked on the component shall be:

- (a) The ESCC Qualified Component symbol (for ESCC qualified components only).
- (b) The ESCC Component Number (see Para. 1.4.2).
- (c) Traceability information.

**2.3 WAFER LOT ACCEPTANCE**

A SEM inspection shall be performed as specified in the ESCC Generic Specification.

**2.4 TERMINAL STRENGTH**

The test conditions for Terminal Strength, tested as specified in the ESCC Generic Specification, shall be as follows:

- Test Condition: A, tension, with an applied force of 40N for a duration of 10s.

**2.5 ELECTRICAL MEASUREMENTS AT ROOM, HIGH AND LOW TEMPERATURES**

Electrical measurements shall be performed at room, high and low temperatures. Consolidated notes are given in Para. 2.5.3.

**2.5.1 Room Temperature Electrical Measurements**

Unless otherwise specified, the measurements shall be performed at  $T_{amb} = +25 \pm 3^{\circ}C$ .

Characteristics	Symbols	MIL-STD-750 Test Method	Test Conditions	Limits		Units
				Min	Max	
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	3407	$V_{GS} = 0V, I_D = 0.25mA$ Bias condition C	250	-	V
Gate-to-Source Threshold Voltage	$V_{GS(th)}$	3403	$V_{DS} \geq V_{GS}, I_D = 1mA$	2	4	V
Gate-to-Source Leakage Current	$I_{GSS}$	3411	$V_{GS} = \pm 20V, V_{DS} = 0V$ Bias condition C	-100	+100	nA
Drain Current	$I_{DSS}$	3413	$V_{GS} = 0V, V_{DS} = 200V$ Bias condition C	-	25	$\mu A$
Static Drain-to-Source On Resistance	$r_{DS(on)}$	3421	$V_{GS} = 10V$ , Note 1 Variants 01, 02: $I_D = 8A$ : Variants 03: $I_D = 29A$ :	-	130 50	m $\Omega$
Source-to-Drain Diode Forward Voltage	$V_{SD}$	4011	$V_{GS} = 0V$ , Note 1 Variants 01, 02: $I_{SD} = 12.4A$ : Variants 03: $I_{SD} = 45A$ :	-	1.2 1.4	V
Thermal Impedance	$Z_{th(j-c)}$	3161	Note 2 Variants 01, 02: $I_H = 2.1A$ : Variant 03: $I_H = 6.7A$ :	-	0.65 0.19	$^{\circ}C/W$

Characteristics	Symbols	MIL-STD-750 Test Method	Test Conditions	Limits		Units
				Min	Max	
Turn-on Delay Time	$t_{d(on)}$	3472	$V_{GS} = 10V, R_G = 4.7\Omega, V_{DS} = 125V$ Note 3 Variants 01, 02: $I_D = 8A$ : Variant 03: $I_D = 29A$	-	25 50	ns
Rise Time	$t_r$	3472	$V_{GS} = 10V, R_G = 4.7\Omega, V_{DS} = 125V$ Note 3 Variants 01, 02: $I_D = 8A$ : Variant 03: $I_D = 29A$ :	-	25 95	ns
Turn-off Delay Time	$t_{d(off)}$	3472	$V_{GS} = 10V, R_G = 4.7\Omega, V_{DS} = 125V$ Note 3 Variants 01, 02: $I_D = 8A$ : Variant 03: $I_D = 29A$ :	-	35 80	ns
Fall Time	$t_f$	3472	$V_{GS} = 10V, R_G = 4.7\Omega, V_{DS} = 125V$ Note 3 Variants 01, 02: $I_D = 8A$ : Variant 03: $I_D = 29A$ :	-	20 75	ns
Reverse Recovery Time	$t_{rr}$	3473	$V_{DD} \leq 50V, di/dt = 100A/\mu s$ Note 3 Variants 01, 02: $I_{SD} = 12.4A$ : Variants 03: $I_{SD} = 45A$ :	-	400 600	ns
Input Capacitance	$C_{iss}$	3431	$V_{GS} = 0V, V_{DS} = 100V, f = 1MHz$ Note 3 Variants 01, 02: Variants 03:	1.3 3.5	1.9 6.5	nF
Output Capacitance	$C_{oss}$	3453	$V_{GS} = 0V, V_{DS} = 100V, f = 1MHz$ Note 3 Variants 01, 02: Variants 03:	90 250	150 400	pF
Reverse Transfer Capacitance	$C_{rss}$	3433	$V_{GS} = 0V, V_{DS} = 100V, f = 1MHz$ Note 3 Variants 01, 02: Variants 03:	1 5	6 20	pF
Total Gate Charge	$Q_g$	3471	$V_{GS} = 10V, V_{DS} = 125V, \text{Note 3}$ Variants 01, 02: $I_D = 12.4A$ : Variants 03: $I_D = 45A$ :	-	42 100	nC
Gate-to-Source Charge	$Q_{gs}$	3471	$V_{GS} = 10V, V_{DS} = 125V, \text{Note 3}$ Variants 01, 02: $I_D = 12.4A$ : Variants 03: $I_D = 45A$ :	-	15 55	nC
Gate-to-Drain Charge	$Q_{gd}$	3471	$V_{GS} = 10V, V_{DS} = 125V, \text{Note 3}$ Variants 01, 02: $I_D = 12.4A$ : Variants 03: $I_D = 45A$ :	-	15 35	nC

2.5.2 High and Low Temperatures Electrical Measurements

Characteristics	Symbols	MIL-STD-750 Test Method	Test Conditions (Note 4)	Limits		Units
				Min	Max	
Gate-to-Source Threshold Voltage	$V_{GS(th)}$	3403	$T_{amb} = +125 (+0 -5)^{\circ}C$ $V_{DS} \geq V_{GS}, I_D = 1mA$	1.5	-	V
			$T_{amb} = -55 (+5 -0)^{\circ}C$ $V_{DS} \geq V_{GS}, I_D = 1mA$	-	5	V
Gate-to-Source Leakage Current	$I_{GSS}$	3411	$T_{amb} = +125 (+0 -5)^{\circ}C$ $V_{GS} = \pm 20V, V_{DS} = 0V$ Bias condition C	-200	+200	nA
Drain Current	$I_{DSS}$	3413	$T_{amb} = +125 (+0 -5)^{\circ}C$ $V_{GS} = 0V, V_{DS} = 200V$ Bias condition C	-	250	$\mu A$
Static Drain-to-Source On Resistance	$r_{DS(on)}$	3421	$T_{amb} = +125 (+0 -5)^{\circ}C$ $V_{GS} = 10V, \text{Note 1}$			m $\Omega$
			Variants 01, 02: $I_D = 8A$ : Variants 03: $I_D = 29A$ :	-	300	-

2.5.3 Notes to Room, High and Low Temperatures Electrical Measurements

1. Pulsed measurement: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
2. The  $Z_{th(j-c)}$  limit is guaranteed by performing a  $\Delta V_{SD}$  (go-no-go) test. The following test conditions and limits shall also apply:
  - $V_{DS} = 20V$
  - $t_M < 75\mu s$
  - $I_M = 10mA$
  - $t_H = 25ms$
  - $V_{SD} = 40mV$  minimum,  $60mV$  maximum
3. Read and record measurements shall be performed on a sample of 32 components with 0 failures allowed. Alternatively a 100% inspection may be performed.
4. Read and record measurements shall be performed on a sample of 5 components with 0 failures allowed. Alternatively a 100% inspection may be performed.

2.6 PARAMETER DRIFT VALUES

Unless otherwise specified, the measurements shall be performed at  $T_{amb} = +25 \pm 3^{\circ}C$ .

The test methods and test conditions shall be as per the corresponding test defined in Para. 2.5.1 Room Temperature Electrical Measurements.

The drift values ( $\Delta$ ) shall not be exceeded for each characteristic specified. The corresponding absolute limit values for each characteristic shall not be exceeded.

Characteristics	Symbols	Limits			Units
		Drift Value $\Delta$	Absolute		
			Min	Max	
Gate-to-Source Threshold Voltage	$V_{GS(th)}$	$\pm 20\%$	2	4	V
Gate-to-Source Leakage Current	$I_{GSS}$	$\pm 20$ or (1) $\pm 100\%$	-100	+100	nA
Drain Current	$I_{DSS}$	$\pm 10$ or (1) $\pm 100\%$	-	25	$\mu A$
Static Drain-to-Source On Resistance (Note 2)	$r_{DS(on)}$				$m\Omega$
Variants 01, 02:		$\pm 20\%$ (3)	-	130	
Variants 03:		$\pm 20\%$ (3)	-	50	

**NOTES:**

1. Whichever is the greater.
2. Measured only prior to HTRB Burn-in and after HTGB Burn-in.
3. Referred to the measurement prior to HTRB Burn-in.

2.7 INTERMEDIATE AND END-POINT ELECTRICAL MEASUREMENTS

Unless otherwise specified, the measurements shall be performed at  $T_{amb} = +25 \pm 3^{\circ}\text{C}$ .

The test methods and test conditions shall be as per the corresponding test defined in Para. 2.5.1 Room Temperature Electrical Measurements.

The limit values for each characteristic shall not be exceeded.

Characteristics	Symbols	Limits			Units
		Drift Value $\Delta$	Absolute		
			Min	Max	
Gate-to-Source Threshold Voltage	$V_{GS(th)}$	$\pm 20\%$	2	4	V
Gate-to-Source Leakage Current	$I_{GSS}$	$\pm 20$ or (1) $\pm 100\%$	-100	+100	nA
Drain Current	$I_{DSS}$	$\pm 10$ or (1) $\pm 100\%$	-	25	$\mu\text{A}$
Static Drain-to-Source On Resistance	$r_{DS(on)}$				$\text{m}\Omega$
	Variants 01, 02:	$\pm 20\%$	-	130	
	Variants 03:	$\pm 20\%$	-	50	

**NOTES:**

1. Whichever is greater.

2.8 HIGH TEMPERATURE REVERSE BIAS BURN-IN CONDITIONS

HTRB Burn-in shall be performed in accordance with [MIL-STD-750, Test Method 1042](#), Test Condition A with the following conditions:

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	$T_{amb}$	+150 (+0 -5)	$^{\circ}\text{C}$
Drain-to-Source Voltage	$V_{DS}$	200 (Note 1)	V
Gate-to-Source Voltage	$V_{GS}$	0	V
Duration	t	240 minimum	Hours

**NOTES:**

1. Voltage may be switched off during cool down.

2.9 HIGH TEMPERATURE STEADY-STATE GATE BIAS BURN-IN CONDITIONS

HTGB Burn-in shall be performed in accordance with MIL-STD-750, Test Method 1042, Test Condition B with the following conditions:

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	$T_{amb}$	+150 (+0 -5)	°C
Drain-to-Source Voltage	$V_{DS}$	0	V
Gate-to-Source Voltage	$V_{GS}$	16	V
Duration	t	48 minimum	Hours

2.10 OPERATING LIFE CONDITIONS

Operating Life shall consist of High Temperature Reverse Bias in accordance with MIL-STD-750, Test Method 1042, Test Condition A, followed by High Temperature Steady-State Gate Bias in accordance with MIL-STD-750, Test Method 1042, Test Condition B. The test conditions are as follows:

High Temperature Reverse Bias Conditions

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	$T_{amb}$	+150 (+0 -5)	°C
Drain-to-Source Voltage	$V_{DS}$	200 (Note 1)	V
Gate-to-Source Voltage	$V_{GS}$	0	V
Duration	t	1000 minimum	Hours

High Temperature Steady State Gate Bias Conditions

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	$T_{amb}$	+150 (+0 -5)	°C
Drain-to-Source Voltage	$V_{DS}$	0	V
Gate-to-Source Voltage	$V_{GS}$	16	V
Duration	t	1000 minimum	Hours

**NOTES:**

1. Voltage may be switched off during cool down.

2.11 TOTAL DOSE RADIATION TESTING

2.11.1 Bias Conditions and Total Dose Level for Total Dose Radiation Testing

The following bias condition shall be used during irradiation testing:

- $V_{GS} = +15V$
- $V_{DS} = 0V$

The total dose level applied shall be as specified in Para. 1.4.2 or in the Purchase Order.



2.11.2 Electrical Measurements for Total Dose Radiation Testing

Prior to irradiation testing the devices shall have successfully met Para. 2.5.1 Room Temperature Electrical Measurements.

Unless otherwise stated the measurements shall be performed at  $T_{amb} = +25 \pm 3^{\circ}\text{C}$ .

Unless otherwise specified the test methods and test conditions shall be as per the corresponding test defined in Para. 2.5.1 Room Temperature Electrical Measurements.

The parameters to be measured during irradiation testing and on completion of irradiation testing are shown below:

Characteristics	Symbols	Limits			Units
		Drift Values ( $\Delta$ )	Absolute		
			Min	Max	
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$\pm 20\%$	250	-	V
Gate-to-Source Threshold Voltage	$V_{GS(th)}$	+10%, -50%	2	4	V
Gate-to-Source Leakage Current	$I_{GSS}$	$\pm 20$	-100	+100	nA
Drain Current	$I_{DSS}$	-	-	25	$\mu\text{A}$
Static Drain-to-Source On Resistance	$r_{DS(on)}$				$\text{m}\Omega$
Variants 01, 02:		$\pm 20\%$		130	
Variants 03:		$\pm 20\%$	-	50	
Source-to-Drain Diode Forward Voltage	$V_{SD}$	$\pm 10\%$			V
Variants 01, 02:			-	1.2	
Variants 03:			-	1.4	

**APPENDIX 'A'**  
**AGREED DEVIATIONS FOR INFINEON TECHNOLOGIES (D)**

ITEMS AFFECTED	DESCRIPTION OF DEVIATIONS
Para. 2.1.1 Deviations from the Generic Specification: Deviations from Production Control - Chart F2	The 3 component sample Dimension Check need only be performed once on each component package production lot.
Para. 2.1.1 Deviations from the Generic Specification: Deviations from Qualification and Periodic Tests - Chart F4	Temperature Cycling shall be performed in accordance with <a href="#">MIL- STD-883, Test Method 1010</a> , Test Condition C, 100 cycles at maximum storage temperature rating specified in the Detail Specification.
	Seal, Fine Leak shall be performed in accordance with <a href="#">MIL-STD-883, Test Method 1014</a> , Test Condition A1 or A2.
Para. 2.1.1.1 Deviations from Screening Tests - Chart F3	Temperature Cycling shall be performed in accordance with <a href="#">MIL-STD-883, Test Method 1010</a> , Test Condition C, 20 cycles at maximum storage temperature rating specified in the Detail Specification.
	High and Low Temperatures Electrical Measurements may be performed at any point after High Temperature Steady-State Gate Bias Burn-in, prior to Seal, but shall still count towards Check for Lot Failure.
	Seal, Fine Leak shall be performed in accordance with <a href="#">MIL-STD-883, Test Method 1014</a> , Test Condition A1 or A2.
	Solderability is not applicable unless otherwise stipulated in the Purchase Order.
Para. 2.5.1 Room Temperature Electrical Measurements	The read and record 32 component sample electrical measurements for characteristics $t_{d(on)}$ , $t_r$ , $t_{d(off)}$ , $t_f$ , $t_{rr}$ , $C_{iss}$ , $C_{oss}$ , $C_{rss}$ , $Q_g$ , $Q_{gs}$ and $Q_{gd}$ need only be performed once on each wafer lot used to supply components to this specification. Any failure shall result in rejection of the wafer lot. The sample measurement may be performed at any time during production.

ADDITIONAL DATA – INFINEON TECHNOLOGIES (D)

(a) Derating for Space Application

These components are susceptible to Single Event Gate Rupture if operated in a space environment unless the following derating is applied:

Single Event Safe Operating Area

